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## PATENT ABSTRACTS OF JAPAN

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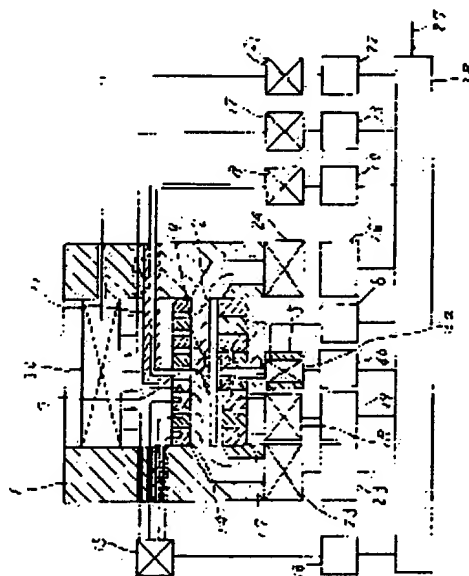
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## (54) COATING DEVICE

## (57)Abstract:

PURPOSE: To make optimum control of a coating condition and to form a coated film to an accurate thickness by making overall control of the temp., humidity, wind flow rate, etc., in a coating chamber according to coating conditions.

CONSTITUTION: The temp. distribution of a semiconductor 2 is controlled in a stationary state by the temp. value of a vacuum suction stage 3, the temp. value of a resist 9, the temp. distribution of a lower cup part 17, the temp. value of the gas to be supplied into a coating cup 1, and further the temp. distribution value of a gaseous flow control part 14 in the formation of a thin film by utilizing a spin coater. The flow rate of the gas acting on a semiconductor wafer 1 is controlled by the values of the exhausting rates from exhausting parts (I)23, (II)24 by control parts (I)25, (II)26 for the exhausting rates and the bore of the vent port of the gaseous flow control part 14. The humidity is controlled in a temp. humidity control part 22, an adjustment part 21 and control part 20. The coating condition is thus subjected to the optimum control and the coated film is



formed with the good accuracy of the film thickness.

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## LEGAL STATUS

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